Tin-Lead
SLOTOLET KB 20

Tin-Lead SLOTOLET KB 20 is a fluoride-free electrolyte for the deposition of semi-bright tin-lead coatings and is applied in high-speed plating lines for plating of IC-leadframes.

Tin-Lead SLOTOLET KB 20 is operated at temperatures between 20 - 40° C with a current density of 10 - 20 A/dm².

Tin-Lead SLOTOLET KB 20 is suitable for plating of zirconium-copper alloys. The additive system prevents the formation of dendrites.

The coatings show excellent solderability, even after accelerated ageing tests. The co-deposition of organics is very low - the carbon content of the deposit is only 0.006%.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.